

- Member of Texas Instruments' Widebus+™ Family
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Flow-Through Architecture Optimizes PCB Layout
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description

The SN74CBT34X245 provides 32 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as four 8-bit bus switches, two 16-bit bus switches, or one 32-bit bus switch. When output enable (\overline{OE}) is low, the switch is on, and port A is connected to port B. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

DBB PACKAGE (TOP VIEW)

NC	1	80	V_{CC}
1A1	2	79	$\overline{1OE}$
1A2	3	78	1B1
1A3	4	77	1B2
1A4	5	76	1B3
1A5	6	75	1B4
1A6	7	74	1B5
1A7	8	73	1B6
1A8	9	72	1B7
GND	10	71	1B8
NC	11	70	V_{CC}
2A1	12	69	$\overline{2OE}$
2A2	13	68	2B1
2A3	14	67	2B2
2A4	15	66	2B3
2A5	16	65	2B4
2A6	17	64	2B5
2A7	18	63	2B6
2A8	19	62	2B7
GND	20	61	2B8
NC	21	60	V_{CC}
3A1	22	59	$\overline{3OE}$
3A2	23	58	3B1
3A3	24	57	3B2
3A4	25	56	3B3
3A5	26	55	3B4
3A6	27	54	3B5
3A7	28	53	3B6
3A8	29	52	3B7
GND	30	51	3B8
NC	31	50	V_{CC}
4A1	32	49	$\overline{4OE}$
4A2	33	48	4B1
4A3	34	47	4B2
4A4	35	46	4B3
4A5	36	45	4B4
4A6	37	44	4B5
4A7	38	43	4B6
4A8	39	42	4B7
GND	40	41	4B8

NC – No internal connection



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SN74CBT34X245 32-BIT FET BUS SWITCH

SCDS089C – MAY 1999 – REVISED MAY 2001

ORDERING INFORMATION

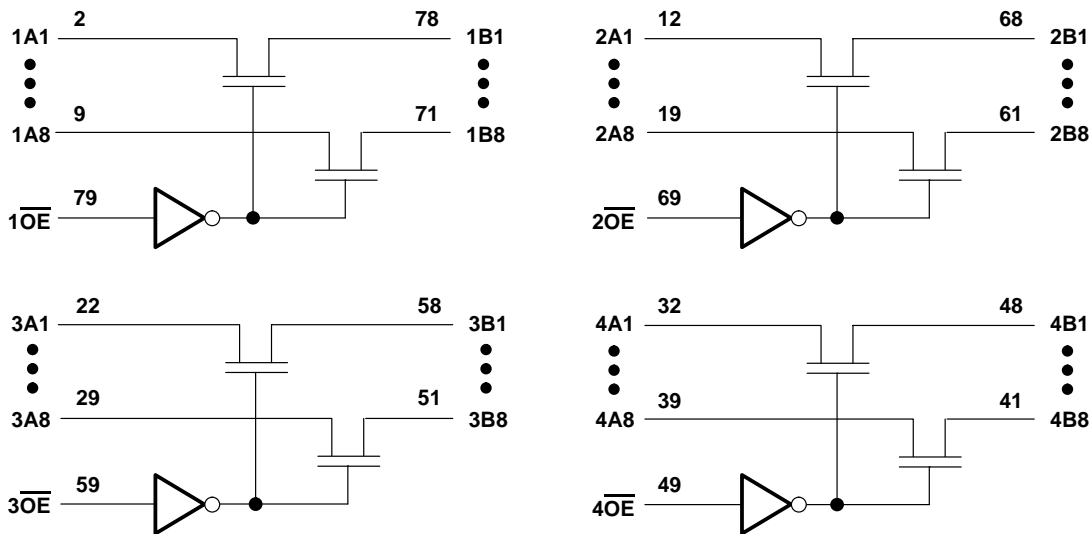
T _A	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TVSOP – DBB Tape and reel	SN74CBT34X245DBBR	CBT34X245

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each 8-bit bus switch)

INPUT OE	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I _{IK} (V _{I/O} < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2)	64°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.2	V
I _I	V _{CC} = 5.5 V, V _I = 5.5 V or GND			±5	μA
I _{off}	V _{CC} = 0, V _I or V _O = 0 to 5.5 V			10	μA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			6	μA
ΔI _{CC} ‡	Control inputs V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			3.5	mA
C _i	Control inputs V _I = 3 V or 0		3.5		pF
C _{io(OFF)}	V _O = 3 V or 0, $\overline{OE} = V_{CC}$		5.5		pF
r _{on} §	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA	11	17	Ω
	V _{CC} = 4.5 V	V _I = 0, I _I = 64 mA	5	7	
		I _I = 30 mA	5	7	
		V _I = 2.4 V, I _I = 15 mA	8	13	

† All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

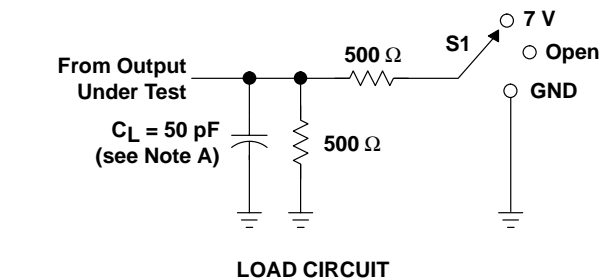
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} ¶	A or B	B or A			0.25		ns
t _{en}	\overline{OE}	A or B	2.2	6.5	1.9	6	ns
t _{dis}	\overline{OE}	A or B	1.9	6.2	2.2	6.7	ns

¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

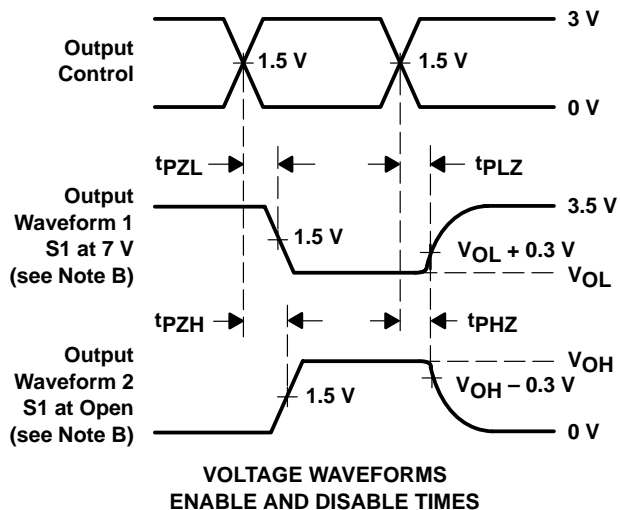
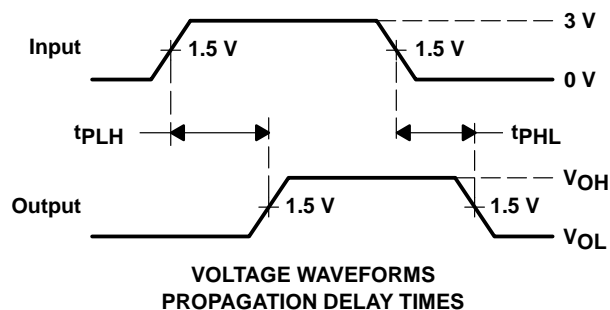
SN74CBT34X245 32-BIT FET BUS SWITCH

SCDS089C – MAY 1999 – REVISED MAY 2001

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74CBT34X245DBBR	ACTIVE	TSSOP	DBB	80	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT34X245	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

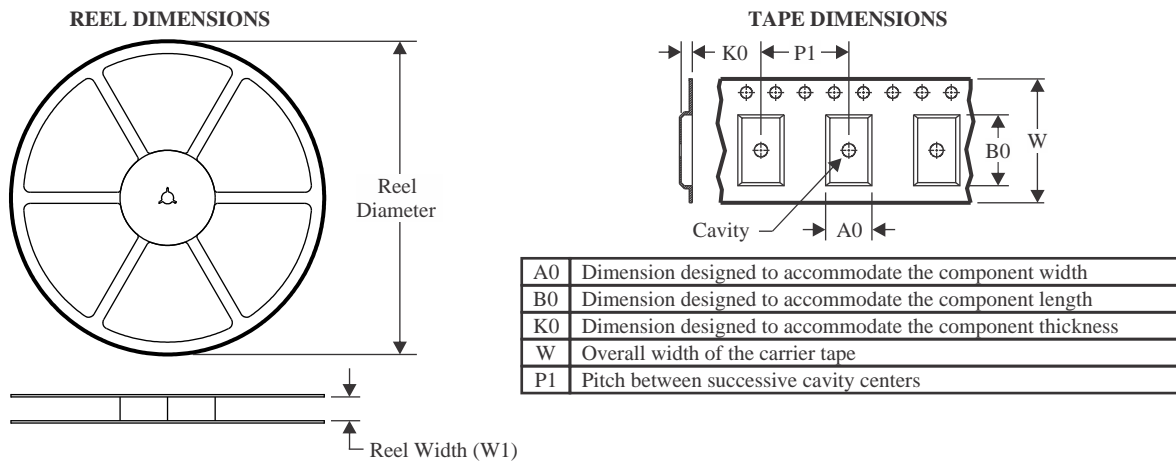
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

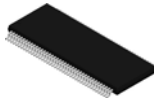
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT34X245DBBR	TSSOP	DBB	80	2000	330.0	24.4	8.4	17.3	1.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT34X245DBBR	TSSOP	DBB	80	2000	356.0	356.0	41.0

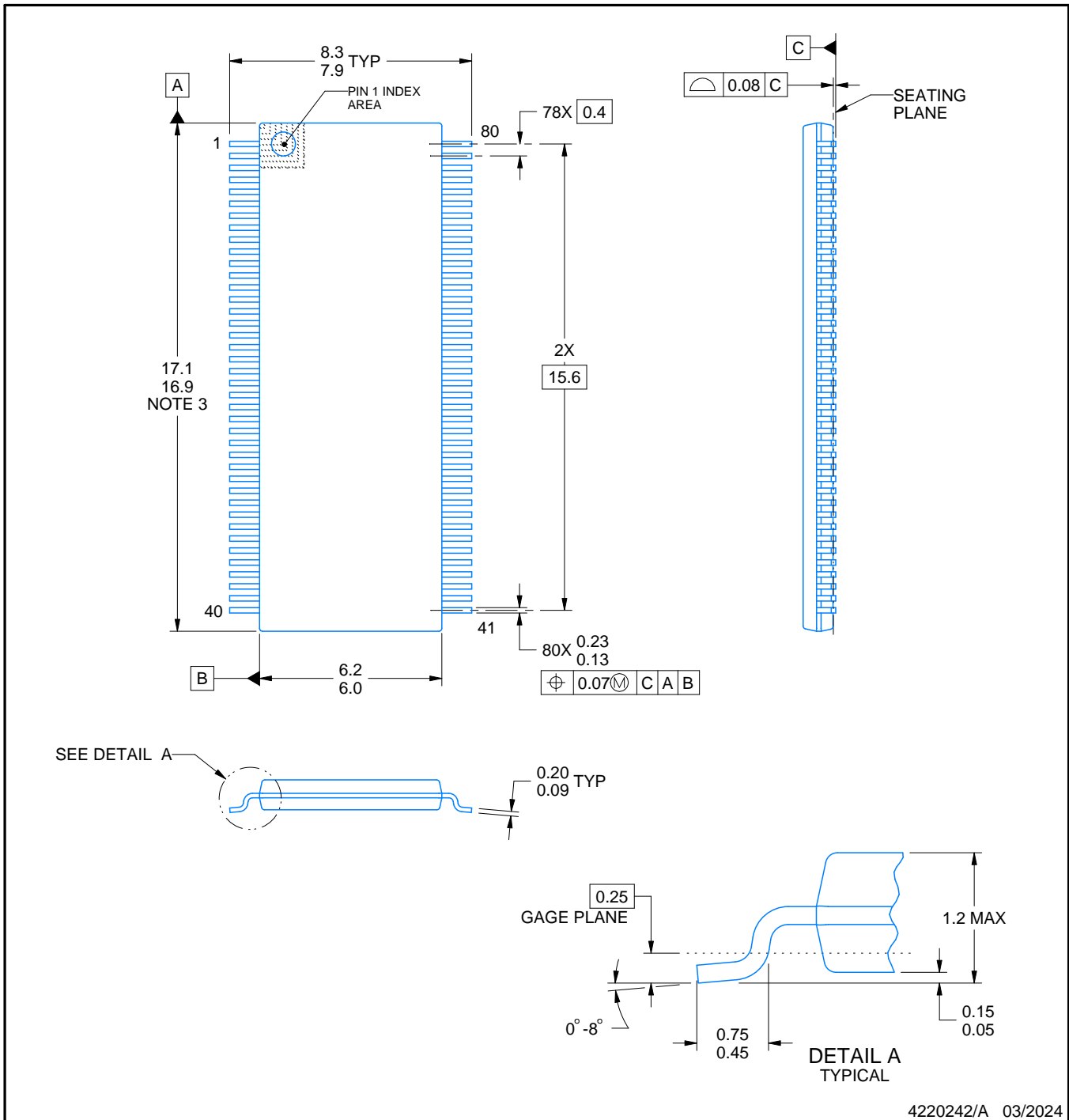
DBB0080A



PACKAGE OUTLINE

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220242/A 03/2024

NOTES:

PowerPAD is a trademark of Texas Instruments.

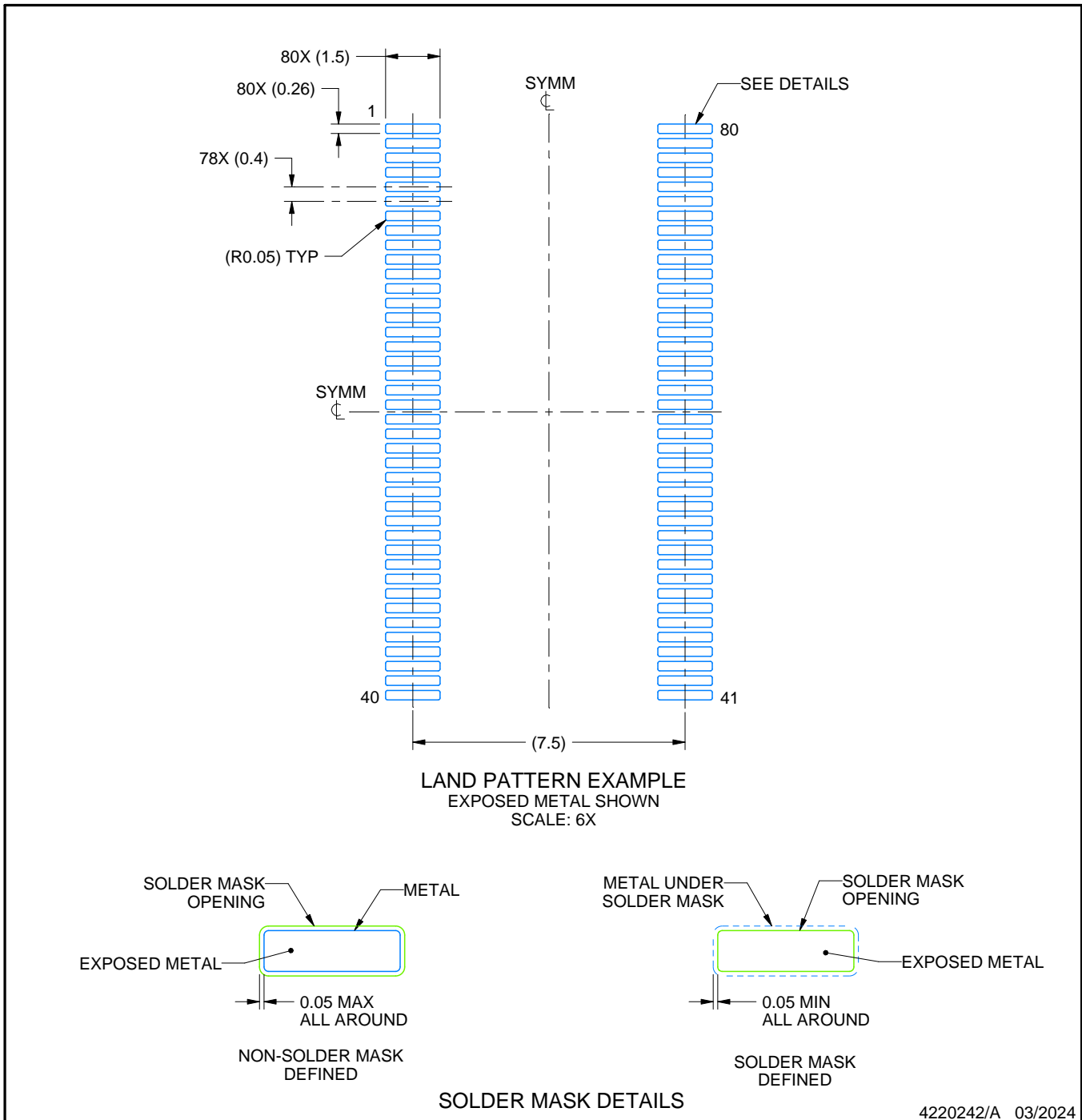
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153, Variation FF.

EXAMPLE BOARD LAYOUT

DBB0080A

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

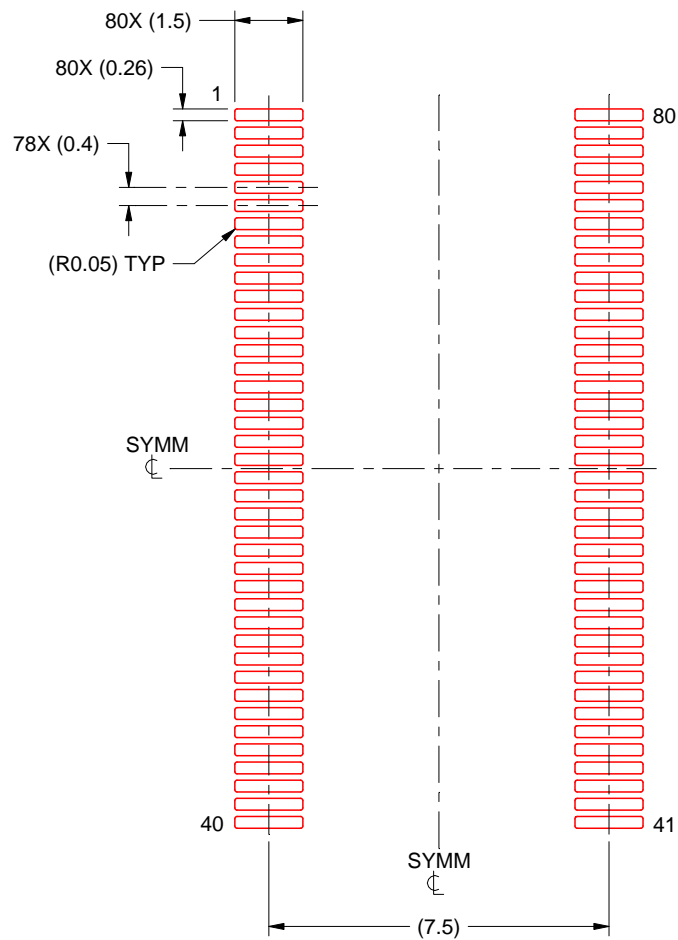
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
8. Size of metal pad may vary due to creepage requirement.
9. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DBB0080A

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 6X

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NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

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